

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Please amend claims 1-29 as follows:

Listing of Claims:

1. (Currently Amended) A process for fabricating electronic components, in which a first anodizing operation is carried out on a support material (1) in order to form at least one first pore (3) that extends, in this support material (1), along a first direction, ~~characterized in that comprising~~ a second anodizing operation is carried out in order to form at least one second pore (17) that extends in the support material (1) along a second direction, different from the first direction..
2. (Currently Amended) The process as claimed in claim 1, ~~in which~~ wherein an insulating material is formed in the first pore (3).
3. (Currently Amended) The process as claimed in ~~either of the preceding claims, in which claim 1, wherein~~ an active material (18) is formed in the second pore (17).
4. (Currently Amended) The process as claimed in claim 3, ~~in which~~ wherein the active material (18) is chosen from a conductor, a semiconductor, a superconductor, a magnetic material and a carbon structure.
5. (Currently Amended) The process as claimed in ~~either of claims 3 and 4, in which claim 3, wherein~~ the active material (10) is deposited in the second pore (17) by electrodeposition
6. (Currently Amended) The process as claimed in claim 5, ~~in which~~ wherein the active material is a semiconductor material transparent to light.

7. (Currently Amended) The process as claimed in claim 6, ~~in which~~ wherein the semiconductor material is an organic material.
8. (Currently Amended) The process as claimed in ~~one of the preceding claims,~~ in which claim 1, wherein the support material (1) constitutes both a self-supporting structure for a components (100) and electrical contact means.
9. (Currently Amended) The process as claimed in ~~one of the preceding claims,~~ in which claim 1, wherein a transistor (100) is produced, the source and drain contacts of which are each at one of the ends of the second pore (17), respectively, and a gate contact is produced by depositing a conducting material (13) on the surface layer (5)
10. (Currently Amended) The process as claimed in ~~one of the preceding claims,~~ in which claim 1, wherein the support material (1) is in the form of a position of a wire extending longitudinally parallel to the second direction
11. (Currently Amended) The process as claimed in the claim 10, ~~in which~~ wherein a plurality of pores, including the first pore, are formed, each extending substantially over the thickness of a surface layer (5) of the wire, radically perpendicular to the second direction.
12. (Currently Amended) The process as claimed in claim 11, ~~in which~~ wherein the surface layer (5) of the wire constitutes a layer of dielectric.
13. (Currently Amended) The process as claimed in ~~one of claims 1 to 8,~~ in which claim 1, wherein at least one active element is enveloped in a matrix comprising the support material (1).
14. (Currently Amended) The process as claimed in claim 13, ~~in which~~ wherein an electrically conducting material is deposited in at least one of the first (3) and second (17) pores

15 (Currently Amended) The process as claimed in ~~either of claims 13 and 14, in which~~ claim 13, wherein a thermally conducting material is deposited in at least one of the first (3) and second (17) pores.

16 (Currently Amended) The process as claimed in ~~one of claims 13 and 15, in which~~ claim 13, wherein an optically conducting material is deposited in at least one of the first (3) and second (17) pores.

17 (Currently Amended) The process as claimed in ~~one of claims 13 to 16, in which~~ claim 13, wherein at least one line of a material chosen from an electrically conducting material, a thermally conducting material and an optically conducting material is produced on the surface of the support material (1), in order to connect the active element to an external element.

18 (Currently Amended) The process as claimed in ~~one of the preceding claims, which~~ comprises claim 1, wherein at least three treatment steps in liquid medium, including the first anodizing operation, the second anodizing operation and an electrodeposition step.

19 (Currently Amended) An electronic component obtained by the process as claimed in ~~one of the preceding claims, comprising~~ claim 1, further including an element of support material (1) with at least one first pore that extends along a first direction and at least one second pore (17) that extends along a second direction, different from the first direction.

20 (Currently Amended) The component as claimed in claim 19, ~~in which~~ wherein the second pore (17) is at least partly filled with an active material (18).

21 (Currently Amended) The component as claimed in claim 20, ~~in which~~ wherein the active material (18) is chosen from a conductor, a semiconductor, a superconductor, a magnetic material and a carbon structure.

22. (Currently Amended) The component as claimed in ~~either of claims 20 and 21, in which~~ claim 20, wherein the active material is transparent to light.

23 (Currently Amended) The component as claimed in ~~one of the claims 20 to 22, in which~~ claim 20, wherein the active material (18) is an organic material

24. (Currently Amended) The component as claimed in ~~one of claims 20 to 23, in which~~ claim 20, wherein a first electrical contact is produced between the active material and the support material, on the bottom of the second pore

25. (Currently Amended) The component as claimed in ~~one of claims 19 to 24, in which~~ claim 19, wherein the support material constitutes both a self-supporting structure for the component and electrical contact means (24)

26. (Currently Amended) The component as claimed in ~~one of claims 19 to 25, in which~~ claim 19, wherein the element of support material is in the form of a wire portion that extends longitudinally parallel to the second direction

27. (Currently Amended) The component as claimed in claim 26, ~~in which~~ wherein the wire portion includes, at the second pore (17), a surface layer (5) consisting of an electrically insulating material

28. (Currently Amended) The component as claimed in claim 27, ~~in which~~ wherein a second electrical contact, radically external with respect to the surface layer (5), is produced on this surface layer (5).

29 (Currently Amended) The component as claimed in ~~one of claims 19 to 25, which~~ includes claim 19, further including at least one active element connected via the first (3) and second (17) pores to the surface of the support material (1)